



QNHCHIP

QNN100P03BJ

Product Specification

QNN100P03BJ

30V P-Channel MOSFET



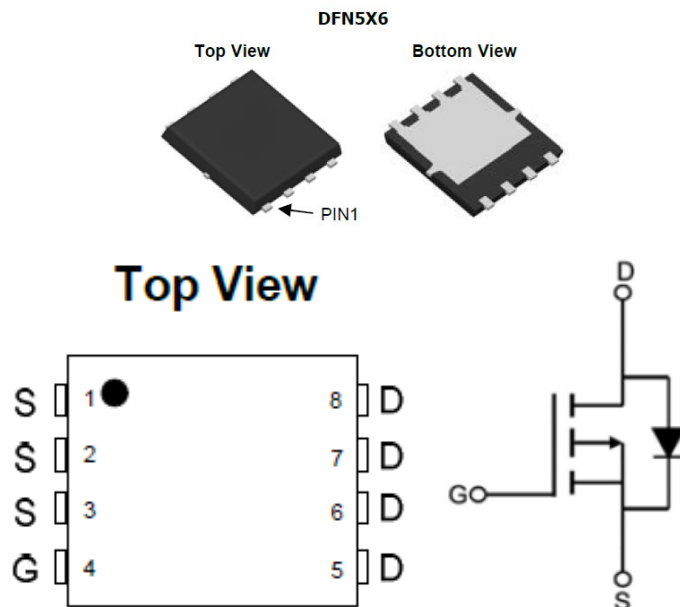
FEATURES

- $V_{DS} = -30V$, $I_D = -80A$
 $R_{DS(ON)}$ TYP. = $3.9m\Omega$ @ $V_{GS} = -10V$
 $R_{DS(ON)}$ TYP.= $5.4m\Omega$ @ $V_{GS} = -4.5V$
- Advanced Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- Lead free product is acquired

Applications

- PWM Applications
- Load Switch
- Power Management

Pin Description



NO.	Symbol	Description
1	S	SOURCE
2	S	SOURCE
3	S	SOURCE
4	G	GATE
5	D	DRAIN
6	D	DRAIN
7	D	DRAIN
8	D	DRAIN



Absolute Maximum Ratings

(@ $T_C = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Value	Unit	
V_{DS}	Drain-to-Source Voltage	-30	V	
V_{GS}	Gate-to-Source Voltage	± 20	V	
I_D	Continuous Drain Current	$T_C=25^\circ\text{C}$	-80	A
		$T_C=100^\circ\text{C}$	-57	
I_{DM}	Pulsed Drain Current ⁽¹⁾	320	A	
E_{AS}	Single Pulsed Avalanche Energy ⁽²⁾	363	mJ	
P_D	Power Dissipation	$T_C=25^\circ\text{C}$	52	W
		$T_C=100^\circ\text{C}$	21	
T_J, T_{STG}	Junction & Storage Temperature Range	-55 to 150	$^\circ\text{C}$	

Thermal Characteristics

Symbol	Parameter	Max	Unit
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient ⁽³⁾	43	$^\circ\text{C}/\text{W}$
$R_{\theta JC}$	Thermal Resistance, Junction to Case	2.4	



Electrical Characteristics

(T_J = 25 °C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	I _D =-250uA, V _{GS} =0V	-30	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-30V, V _{GS} =0V	-	-	-1.0	uA
I _{GSS}	Gate-Body Leakage Current	V _{DS} =0V, V _{GS} =±20V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250uA	-1.2	-1.7	-2.2	V
R _{DS(ON)}	Static Drain-Source ON-Resistance ⁽⁴⁾	V _{GS} =-10V, I _D =-20A	-	3.9	5.9	m Ω
		V _{GS} =-4.5V, I _D =-10A	-	5.4	8.0	m Ω
Dynamic Characteristics						
R _g	Gate Resistance	f=1MHz	-	3.9	-	Ω
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =-15V, f=1MHz	-	7747	-	pF
C _{oss}	Output Capacitance		-	871	-	pF
C _{rss}	Reverse Transfer Capacitance		-	559	-	pF
Q _g	Total Gate Charge	V _{GS} =0~-10V, V _{DS} =-15V, I _D =-20A	-	121	-	nC
Q _{gs}	Gate Source Charge		-	23	-	nC
Q _{gd}	Gate Drain("Miller") Charge		-	18	-	nC
Switching Characteristics						
t _{d(on)}	Turn-On DelayTime	V _{GS} =-10V, V _{DD} =-15V, I _D =-20A, R _{GEN} =3 Ω	-	28	-	ns
t _r	Turn-On Rise Time		-	83	-	ns
t _{d(off)}	Turn-Off DelayTime		-	77	-	ns
t _f	Turn-Off Fall Time		-	66	-	ns
Body Diode Characteristics						
I _S	Maximum Continuous Body Diode Forward Current		-	-	-80	A
I _{SM}	Maximum Pulsed Body Diode Forward Current		-	-	-320	A
V _{SD}	Body Diode Forward Voltage	V _{GS} =0V, I _S =-30A	-		1.2	V
t _{rr}	Body Diode Reverse Recovery Time	I _F =-20A, di/dt=100A/us	-	30	-	ns
Q _{rr}	Body Diode Reverse Recovery Charge		-	19.5	-	nC

Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
2. E_{AS} condition: Starting T_J=25 °C, V_{DD}=-15V, V_G=-10V, R_G=25 Ω, L=0.5mH, I_{AS}=-38.08A, V_{DD}=0V during time in avalanche.
3. R_{θJA} is measured with the device mounted on a 1 inch² pad of 2oz copper FR4 PCB.
4. Pulse Test: Pulse Width≤300us, Duty Cycle≤0.5%.



Test Circuit

Figure 1: Gate Charge Test Circuit & Waveform

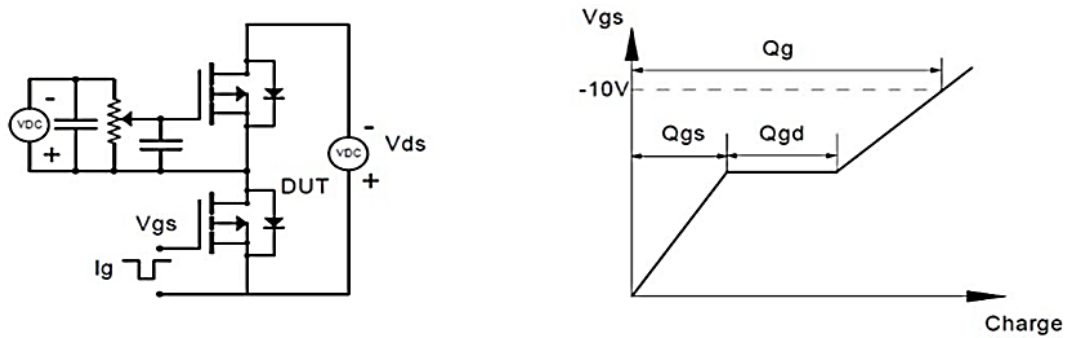


Figure 2: Resistive Switching Test Circuit & Waveform

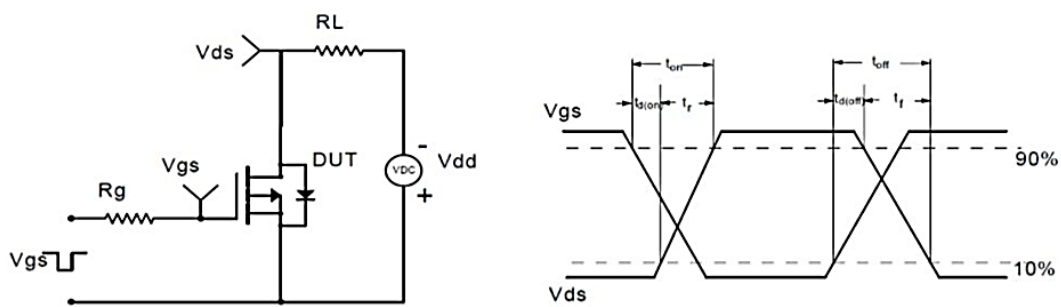


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

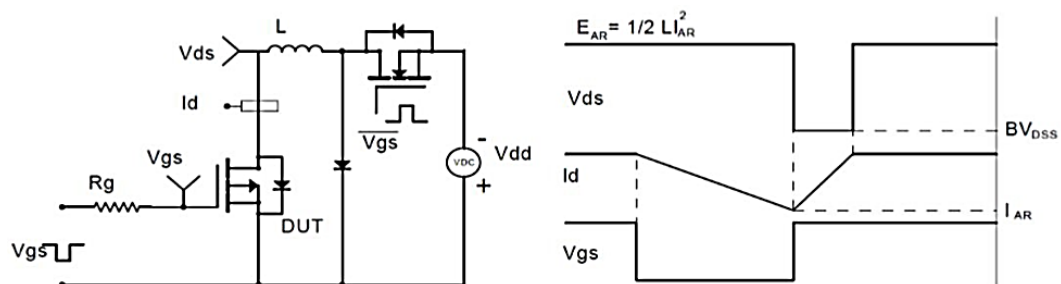
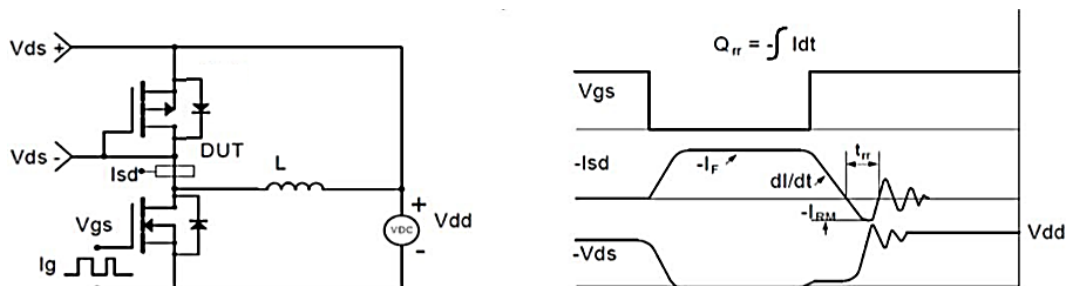
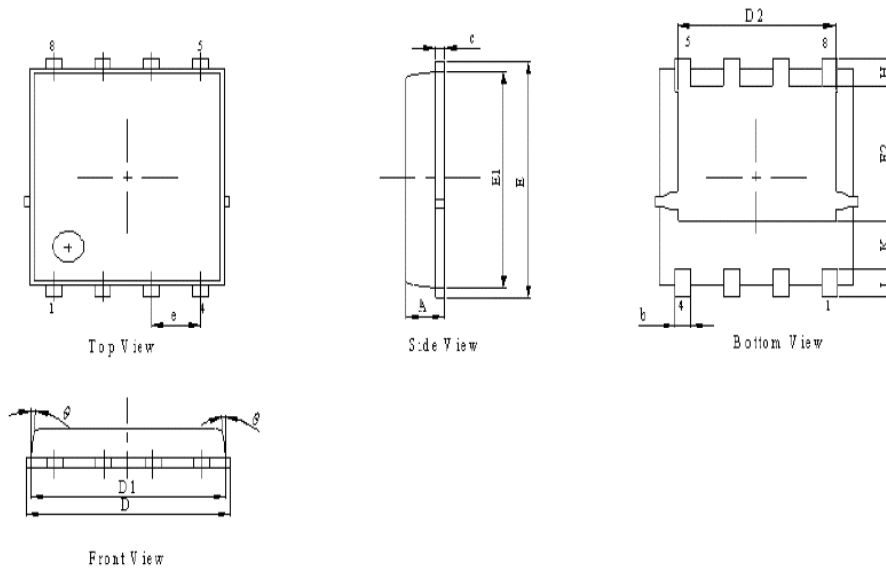


Figure 4: Diode Recovery Test Circuit & Waveform

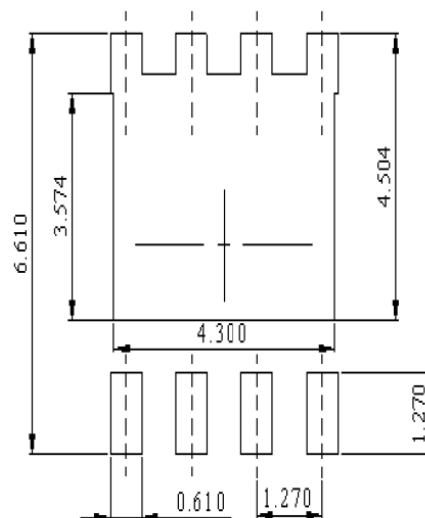




Package Mechanical Data(PDFN 5x6-8L)



Symbol	Dimensions In Millimeters		
	Min.	NOM.	Max.
A	0.9	1	1.15
b	0.31	0.41	0.51
C	0.24	0.32	0.4
D	5	5.2	5.4
D1	4.95	5.05	5.15
D2	4	4.1	4.2
E	6.05	6.15	6.25
E1	5.5	5.6	5.7
E2	3.42	3.53	3.63
e	1.27 BSC		
H	0.6	0.7	0.8
L	0.5	0.7	0.8
K	1.23 BEF		
O			10



DIMENSIONS: MILLIMETERS



Ordering information

Order Code	Package	V _{DS} (V)	I _D (A)	R _{DS(ON)} (mΩ)	
QNN100P03BJ	PDFN 5x6-8L	-30	-80	V _{GS} =-10V	3.9
				V _{GS} =-4.5V	5.4